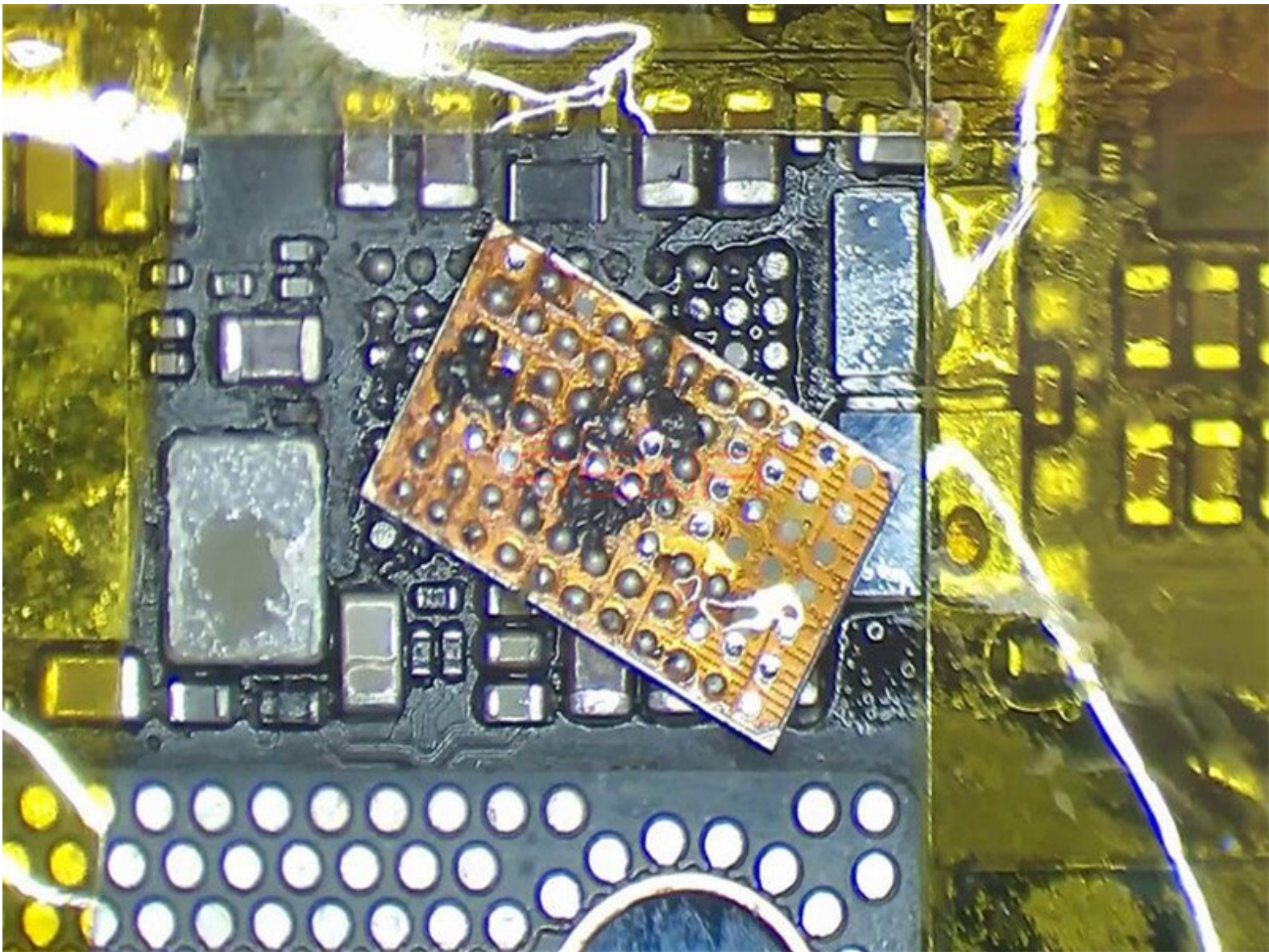




# iPhone X Water Damage Troubleshooting

iPhone X/XS/XS Max Water Damage Troubleshooting

Written By: Phryne



## INTRODUCTION

iPhone water damage has always been a frustrating and difficult issue for repair technicians. Things can also be much more difficult when it comes with iPhone X/XS/XS Max. What you usually do with iPhone water damage repair? Got your unique repair thoughts? Well, don't panic! REWA iPhone X water damage repair guide shall definitely enlighten you.



### TOOLS:

- [Heating Platform](#) (1)
- [BGA Reballing Fixture For iPhone X/XS/XS Max](#) (1)

## Step 1 — Problem



- Press the power button to turn on the phone. There is no response at all.
- Let's take apart the phone and remove the display assembly first.
- Connect the battery connector with the DC Power Supply. Current reading on the ammeter jumps to 100mA and then stays still, which is abnormal.

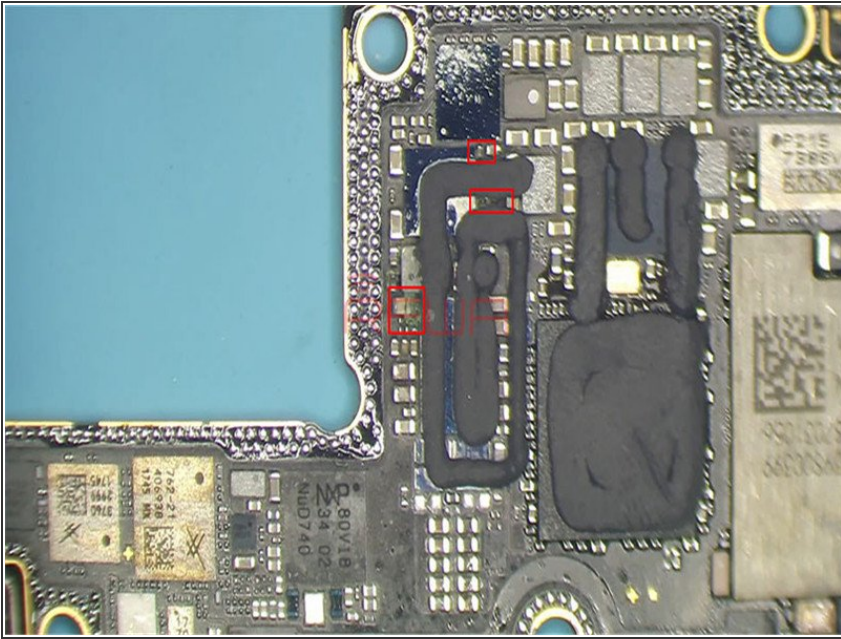
## Step 2 — Motherboard Separating



- The first thing we do is to separate the upper layer from the lower layer with the help of the specialized Heating Platform.

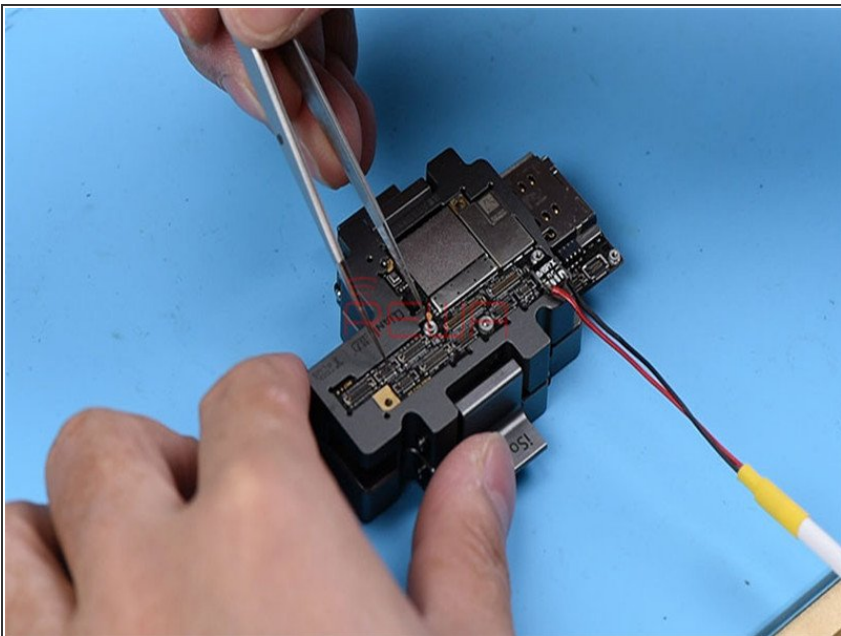


## Step 3 — Fault Finding



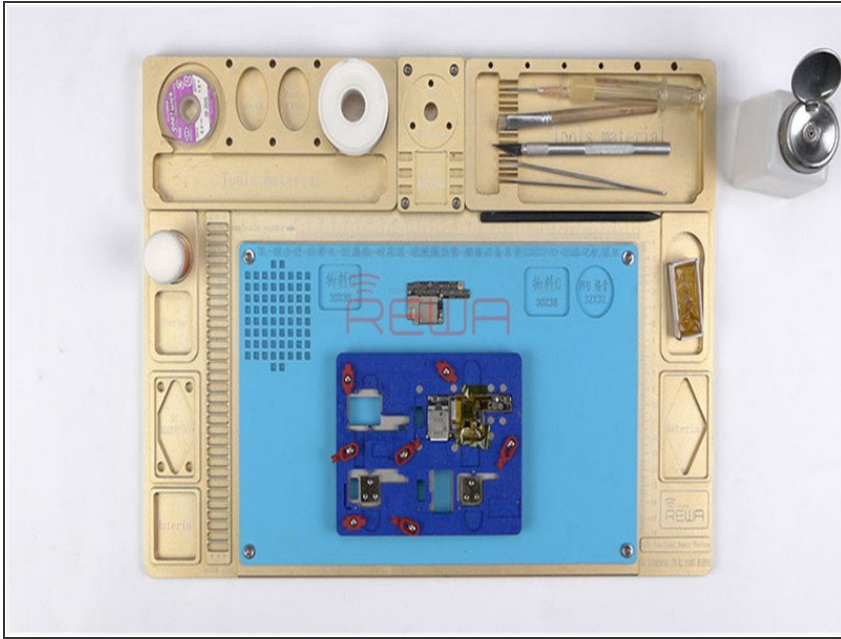
- Check the two layers under the Microscope. Nothing goes wrong with the upper layer.
- Yet areas on the lower layer bear obvious signs of water damage.

## Step 4 — Fault Analyzing



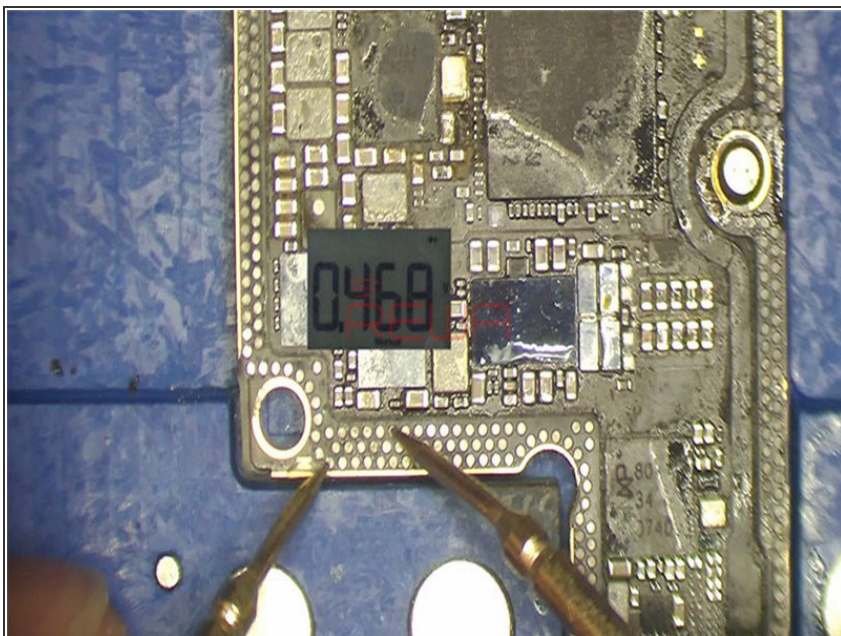
- Attach the upper layer and the lower layer to the test fixture and get the phone powered on with tweezers.
- Current reading on the ammeter jumps to 100mA and then stays still, which is abnormal. Disconnect the power supply.
- Connect the battery connector on the upper layer with the DC Power Supply. Get the phone powered on with tweezers. Current reading on the ammeter is normal this time.
- Judging by this, the fault is probably related to the lower layer.

## Step 5 — Fault Confirming



- Run diode mode measurement of capacitors around the moldy IC U3400, Nothing goes wrong.
- Continue to run diode mode measurement of the third space PCB. The measured value of Pin S30 is 40, which is abnormal.
- Since Pin S30 is connected directly to Pin L4 of U3400, the fault is probably related to U3400. So the next thing we do is to check U3400.
- Remove U3400 with Hot Air Gun. We can see that U3400 and its bonding pad have mildewed severely.

## Step 6 — Fault Clearing



- Replace U3400 with a new IC.
- Again, run diode mode measurement of Pin S30 on the third space PCB. The measured value is normal this time.
- Attach the upper layer and the lower layer to the test fixture. Current reading on the ammeter is normal this time and the phone turns on normally.

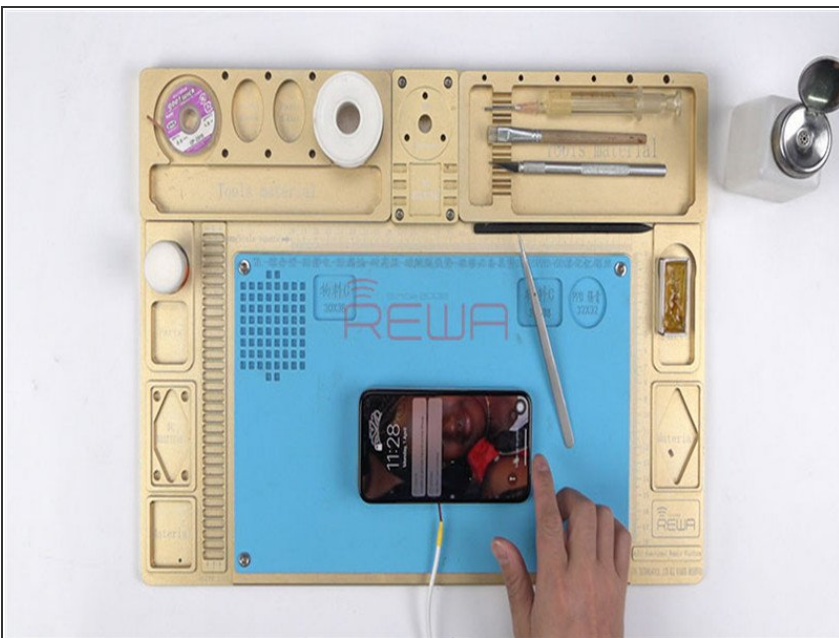


## Step 7 — Motherboard Recombining



- In this step we will use a very useful tool, known as iPhone X specialized reballing mold. It can help us complete the reballing process perfectly.
- With the help of iPhone X specialized Heating Platform, the motherboard recombining process is very easy and efficient.

## Step 8 — Assemble&Test



- Now we can assemble the phone and test.
- Press the power button to turn on the phone. The phone turns on normally.

## Step 9 — Video Guide



- You can also visit [REWA YouTube Channel](#) for more iPhone X repair cases..
- Credit: [REWA Technology](#)